

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S17 0	2143	(438/208,107,109,4,928,915,187, 209,203,86,195).CCLS.	USPAT; USOCR	OR	OFF	2005/07/28 15:10
S17 1	6	S170 and "MCM type"	US-PGPUB; USPAT	OR	ON	2005/07/28 15:12
S17 2	98	S170 and "die bonding"	US-PGPUB; USPAT	OR	ON	2005/07/28 15:29
S17 3	3	S170 and "compact semiconductor device"	US-PGPUB; USPAT	OR	ON	2005/07/28 15:39
S17 4	139	S170 and "mcm"	US-PGPUB; USPAT	OR	ON	2005/07/28 15:41
S17 5	2824	(257/723,787).CCLS.	USPAT; USOCR	OR	OFF	2005/07/29 12:32
S17 6	52	S175 and "insulation film"	US-PGPUB; USPAT	OR	ON	2005/07/29 12:41
S17 7	0	S176 and "single-layer"	US-PGPUB; USPAT	OR	ON	2005/07/29 12:33
S17 8	11	S176 and "die bonding"	US-PGPUB; USPAT	OR	ON	2005/07/29 12:34
S17 9	2140	(257/758,759).CCLS.	USPAT; USOCR	OR	OFF	2005/07/29 15:36
S18 0	21	S179 and "die bonding"	US-PGPUB; USPAT	OR	ON	2005/07/29 15:41
S18 1	239	S179 and insulation with film	US-PGPUB; USPAT	OR	ON	2005/07/29 16:04
S18 2	15	("4630096" or ("4746960") or ("4827328") or ("4860166") or ("4866508") or ("4878991") or ("4884122") or ("4894115") or ("4907062") or ("4933042") or ("5049980") or ("5091769") or ("5111278") or ("5144747") or ("5250843")).PN.	USPAT; USOCR	OR	OFF	2005/07/29 16:09
S18 3	1947	(257/758).CCLS.	USPAT; USOCR	OR	OFF	2005/08/01 08:39
S18 4	5189	((257/685,687,90,723,787) or (438/107,118)).CCLS.	USPAT; USOCR	OR	OFF	2005/08/01 08:40
S18 6	404	S184 and (remove or removal) with substrate	US-PGPUB; USPAT	OR	ON	2005/08/01 09:39
S18 7	133	S184 and substrate adj1 (remove or removal or removed)	US-PGPUB; USPAT	OR	ON	2005/08/01 10:43
S18 8	6	S184 and Si adj substrate adj1 (remove or removal or removed)	US-PGPUB; USPAT	OR	ON	2005/08/01 10:44
S18 9	1	("6159767").PN.	USPAT; USOCR	OR	OFF	2005/08/01 15:50